

Amendment to the Claims

Claims 1-3 (Cancelled)

4. (New) An electroless plating method comprising:
- positioning a substrate so that a surface of thereof, to be plated, is directed downwardly;
- immersing the surface to be plated into an electroless plating treatment liquid in a plating chamber in such a state that the substrate is inclined at a certain angle with respect to a horizontal plane so as to remove gas generated on the surface to be plated; and
- processing the surface to be plated by the electroless plating treatment liquid in the plating chamber.
5. (New) The electroless plating method according to claim 4, further comprising heating the electroless plating treatment liquid on a bottom of the plating chamber.
6. (New) The electroless plating method according to claim 4, further comprising heating the substrate before said immersing operation.
7. (New) The electroless plating method according to claim 6, wherein said heating operation comprises heating the substrate to a temperature that is equal to a temperature of the electroless plating treatment liquid.

8. (New) The electroless plating method according to claim 4, further comprising flowing the electroless plating treatment liquid in the plating chamber at a flow rate of 1 to 30 l/min.

9. (New) An electroless plating method comprising:

positioning a substrate such that a surface thereof, to be plated, is directed downwardly;

flowing an electroless plating treatment liquid as a laminar flow along a quadratic curved surface of a plating chamber so as to remove gas generated on the surface to be plated, the quadratic curved surface spreading upwardly and outwardly;

bringing the surface to be plated into contact with the electroless plating treatment liquid in the plating chamber; and

processing the surface to be plated by the electroless plating treatment liquid in the plating chamber.

10. (New) The electroless plating method according to claim 9, further comprising heating the electroless plating treatment liquid on a bottom of said plating chamber.

11. (New) The electroless plating method according to claim 9, further comprising heating the substrate before the operation of bringing the surface to be plated into contact with the electroless plating treatment liquid in the plating chamber.

12.(New) The electroless plating method according to claim 11, wherein said heating operation comprises heating the substrate to a temperature equal to a temperature of the electroless plating treatment liquid.

13.(New) The electroless plating method according to claim 9, wherein said flowing operation comprises flowing the electroless plating treatment liquid in the plating chamber at a flow rate of 1 to 30 l/min.